

IN THE CLAIMS:

Please amend the claims as follows:

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1. (Canceled)
2. (Currently amended) The method of claim 28, ~~The composition of claim 1,~~ wherein the particles comprise a material selected from a group consisting of a polyacrylate, a polyvinyl alcohol, a polyvinyl benzene, a polyvinylidene chloride, a polymelamine, a polypropylene, a polyethylene, a polystyrene, a polyester, a polyamide, a polyurethane, and any combination thereof.
3. (Currently amended) The method of claim 28, ~~The composition of claim 1,~~ wherein the particles comprise a material selected from polymethyl methacrylate and polybutyl methacrylate.
4. (Currently amended) The method of claim 28, ~~The composition of claim 1,~~ wherein the particles have a functionality selected from a group consisting of hydrophilicity and hydrophobicity.
5. (Currently amended) The method of claim 28, ~~The composition of claim 1,~~ wherein an average diameter of the particles is from about 0.1 to about 1.8 microns.
6. (Currently amended) The method of claim 28, wherein the chemical-mechanical polishing composition further comprises ~~The composition of claim 1, further comprising~~ an oxidizing agent.
7. (Currently amended) The method of claim 28, wherein the chemical-mechanical polishing composition further comprises ~~The composition of claim 1, further comprising~~ an oxidizing agent selected from a group consisting of hydroxylamine, a salt of hydroxylamine, hydrogen peroxide, periodic acid, a peracetic acid, ammonium persulfate, and any combination thereof.

8. (Currently amended) The method of claim 7, wherein the ~~The composition of claim 1, further comprising~~ oxidizing agent ~~that~~ comprises hydroxylamine nitrate.

9. (Currently amended) The ~~composition~~ method of claim 7, wherein the chemical-mechanical polishing composition further comprises ~~further comprising~~ a secondary oxidizing agent selected from a group consisting of a salt of iron, copper, or cesium, a chelated complex of any such salt, nitric acid, and any combination thereof.

10. (Currently amended) The method of claim 28, ~~The composition of claim 1,~~ wherein the polymeric particles in the chemical-mechanical polishing composition has ~~have~~ a zeta potential of from about -60 mV to about 10 mV.

11. (Cancelled)

12. (Currently amended) The method of claim 28, ~~The composition of claim 1,~~ wherein the composition has a pH of from about 4 to about 8.

13. (Currently amended) The method of claim 28, ~~The composition of claim 1,~~ wherein the composition has a pH of from about 5 to about 7.

14. (Currently amended) The method of claim 28, ~~The composition of claim 1,~~ wherein the aqueous solution further comprises ionic species.

15. (Currently amended) The method of claim 29, wherein the A chemical-mechanical polishing composition comprises ~~, comprising:~~

an aqueous solution;

an abrasive comprising polymeric particles selected from a group consisting of a polyacrylate, a polyvinyl alcohol, a polyvinyl benzene, a polyvinylidene chloride, a polymelamine, a polypropylene, a polyethylene, a polystyrene, a polyester, a polyamide, a polyurethane, and any combination thereof, wherein the polymer particles are electrified and the

polymer particles in said aqueous solution having an electrical charge sufficient to create an electrostatic repulsive force between adjacent particles; and

an oxidizing agent selected from a group consisting of hydroxylamine, a salt of hydroxylamine, hydrogen peroxide, periodic acid, a peracetic acid, ammonium persulfate, and any combination thereof.

16. (Currently amended) The ~~composition~~ method of claim 15, wherein the particles comprise a material selected from polymethyl methacrylate and polybutyl methacrylate.

17. (Currently amended) The ~~composition~~ method of claim 15, wherein the particles have a functionality selected from a group consisting of hydrophilicity and hydrophobicity.

18. (Currently amended) The ~~composition~~ method of claim 15, wherein an average diameter of the particles is from about 0.1 to about 1.8 microns.

19. (Currently amended) The ~~composition~~ method of claim 15, wherein the oxidizing agent comprises hydroxylamine nitrate.

20. (Currently amended) The ~~composition~~ method of claim 15, wherein the chemical-mechanical polishing composition further comprises ~~further comprising~~ a secondary oxidizing agent selected from a group consisting of a salt of iron, copper, or cesium, a chelated complex of any such salt, nitric acid, and any combination thereof.

21. (Canceled)

22. (Canceled)

23. (Currently amended) The ~~composition~~ method of claim 15, wherein the composition has a pH of from about 4 to about 8.

24. (Currently amended) The ~~composition~~ method of claim 15, wherein the composition has a pH of from about 5 to about 7.

25. (Currently amended) The ~~composition~~ method of claim 15, wherein the aqueous solution further comprises ionic species.

26. (Currently amended) A method of polishing a substrate surface using a polishing pad, comprising:

providing a substrate having a surface to be polished;

providing the product chemical-mechanical polishing composition resulting from the method of any of claims 1, 6, and 15, on the surface to be polished; and

contacting the surface to be polished having the chemical-mechanical polishing composition thereon with the polishing pad and causing relative motion between the surface and the polishing pad.

27. (Previously presented) The method of claim 26, wherein the surface comprises a feature of a material selected from a group consisting of aluminum, copper, silver, tungsten, any alloy of thereof, and any combination thereof.

28. (Currently amended) A method of preparing a composition for chemical-mechanical polishing, comprising:

providing an aqueous solution;

imparting an electrostatic charge to polymeric particles by passing the particles through an electrostatic field, by friction electrification, or by contact with an electrified surface , ~~the electrical charge sufficient to create an electrostatic repulsive force between proximate particles ;~~ and

adding an abrasive comprising the electrostatically charged polymeric particles to the aqueous solution , wherein the polymeric particles in the aqueous solution have an electrical charge sufficient to create an electrostatic repulsive force between proximate particles.

29. (Currently amended) A method of preparing a composition for chemical-mechanical polishing, comprising:

providing an aqueous solution;

imparting an electrostatic charge to polymeric particles by passing the particles through an electrostatic field, by friction electrification, or by contact with an electrified surface, ~~the electrical charge sufficient to create an electrostatic repulsive force between proximate particles ;~~

adding an abrasive comprising the electrostatically charged polymeric particles to the aqueous solution, wherein the polymeric particles in the aqueous solution have an electrical charge sufficient to create an electrostatic repulsive force between proximate particles; and

adding an oxidizing agent to the aqueous solution.

30. (Previously presented) The method of claim 28 or 29, further comprising adjusting a pH of the composition.

31. (Previously presented) A composition for chemical-mechanical polishing produced according a method of claim 28 or 29.

32. (Currently amended) The ~~composition~~ method of claim 15, wherein the particles were electrified by passing through an electricstatic electrostatic field, ~~by friction electrification,~~ or by contact with an electrified surface.

33. (Currently amended) The ~~composition~~ method of claim 15, wherein the polymer particles have a water content of about 2% or less.

34.(Canceled).